MEST2G-025-10-CM32

Pin Diode Switch Element

Features
- Power Handling 25 W @ 4 GHz or less @ 100 mA
- Low Insertion Loss: <0.4 dB @ 1 - 4 GHz
- Medium Isolation: >10 dB @ 2.0 GHz
- RoHS* Compliant

Description
The MEST2G-025-10-CM32 is a thermal to ground series diode switch element (EST2G) in an Aluminum Nitride package. This part is designed to handle up to 25 watts. Usable up to 4.0 GHz.

Electrical Specifications: \( T_C = +25°C \) (unless otherwise specified)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Test Conditions</th>
<th>Units</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Breakdown Voltage ( (V_{BR}) )</td>
<td>( I_R = 10 \mu A )</td>
<td>V</td>
<td>200</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>Leakage Current ( (I_R) )</td>
<td>( V_R = 100 ) V</td>
<td>nA</td>
<td>40</td>
<td>100</td>
<td></td>
</tr>
<tr>
<td>Forward Voltage ( (V_F) )</td>
<td>( I_F = 100 ) mA</td>
<td>V</td>
<td>---</td>
<td>980</td>
<td></td>
</tr>
<tr>
<td>Series Resistance ( (R_S) )</td>
<td>( I_F = 100 ) mA, 100 MHZ</td>
<td>Ω</td>
<td>---</td>
<td>1.25</td>
<td></td>
</tr>
<tr>
<td>Total Capacitance ( (C_T) )</td>
<td>( V_R = -50 ) V, 1 MHz</td>
<td>pF</td>
<td>---</td>
<td>0.22</td>
<td></td>
</tr>
<tr>
<td>Lifetime ( (t) )</td>
<td>( I_F = 10 ) mA, ( I_R = 6 ) mA, 50%</td>
<td>ns</td>
<td>---</td>
<td>2000</td>
<td></td>
</tr>
<tr>
<td>I-Region ( (w) )</td>
<td>I-Layer</td>
<td>μm</td>
<td>---</td>
<td>140</td>
<td></td>
</tr>
<tr>
<td>Input / Output Return Loss ( (I/OR_L) )</td>
<td>( I_F = 100 ) mA, 2 GHz</td>
<td>dB</td>
<td>27</td>
<td>32</td>
<td>26</td>
</tr>
<tr>
<td>Insertion Loss ( (I_L) )</td>
<td>( I_F = 100 ) mA, 2 GHz</td>
<td>dB</td>
<td>0.06</td>
<td>0.07</td>
<td>0.15</td>
</tr>
<tr>
<td>Isolation ( (I_{ISO}) )</td>
<td>( I_F = 400 ) mA, 2 GHz</td>
<td>dB</td>
<td>8</td>
<td>10</td>
<td>6</td>
</tr>
</tbody>
</table>

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Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Absolute Maximum</th>
</tr>
</thead>
<tbody>
<tr>
<td>Breakdown Voltage (V_{R})</td>
<td>200 V</td>
</tr>
<tr>
<td>Forward Current (I_{FDC})</td>
<td>200 mA</td>
</tr>
<tr>
<td>Thermal Resistance (\theta_{JC})</td>
<td>25°C/W</td>
</tr>
<tr>
<td>Junction Temperature (T_{J})</td>
<td>-40°C to 175°C</td>
</tr>
<tr>
<td>Storage Temperature (T_{STG})</td>
<td>-55°C to +150°C</td>
</tr>
<tr>
<td>Mounting Temperature (T_{MTG})</td>
<td>+260°C per JEDEC STD-J-20C</td>
</tr>
</tbody>
</table>

1. Exceeding any one or combination of these limits may cause permanent damage to this device.
2. MACOM does not recommend sustained operation near these survivability limits.

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these Class 0 (HBM) devices.

Typical Performance Curves: \( T_A = 25°C, Z_O = 50 \, \Omega, -10 \, \text{dBm Small Signal} \)

**Insertion Loss**

![Insertion Loss Graph](image)

**Isolation**

![Isolation Graph](image)

**Input / Output Return Loss**

![Input / Output Return Loss Graph](image)
**Resistance vs. Bias Current, 100 MHz**

![Graph showing resistance vs. bias current](image1)

**Junction Temperature vs. Input Power**

*Mounted on Heat Sink @ $T_A = 25\text{°C}$, 1.3 GHz*

![Graph showing junction temperature vs. input power](image2)

**PCB Layout**

![PCB layout diagram](image3)

Plated through, filled and plated over vias

Solder mask should provide 60um clearance between copper pad and solder mask. Rounded pkg pads should have matching rounded solder mask openings.

Use circles or squares for the thermal land stencil design such that only get 60 to 80% solder paste coverage.
Pin Diode Switch Element

Outline (CM32)

Pin function for Silicon PIN diode.
1. Anode
2. Cathode

Notes:
2. Dimensions in mils [mm]
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